

	Hit s	Search Text	DBs
1	8	(("4294650") or ("5259926") or ("5514503") or ("5544582") or ("5678483") or ("5701815") or ("6001515") or ("6356318")).PN.	US-PGPUB; USPAT
2	407	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	323	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3) and contact\$4 and ((substrate or transfer) same (metal\$4 or semiconductor or "SiO.sub.2" or SiO\$2 or insulat\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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4	222	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3) and contact\$4 and ((substrate or transfer) same (metal\$4 or semiconductor or "SiO.sub.2" or SiO\$2 or insulat\$4)) and (photoresist or resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
5	146	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3) and contact\$4 and ((substrate or transfer) same (metal\$4 or semiconductor or "SiO.sub.2" or SiO\$2 or insulat\$4) same (photoresist or resist))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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6	48	((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3) and ((substrate or transfer) same (metal\$4 or semiconductor or "SiO.sub.2" or SiO\$2 or insulat\$4) same (photoresist or resist)) and ((substrate or clich\$3) same (etch\$4 near5 (object or process\$4)) same (fill\$4 or deposit\$4 or form\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	6	430/322.ccls. and ((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	4	101/153.ccls. and ((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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9	3	430/324.ccls. and ((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	6	101/34.ccls. and ((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	38	"101"/\$.ccls. and ((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
12	50	"430"/\$.ccls. and ((substrate or wafer) same (panel\$3 or unit or clich\$2 or area or region or divid\$3) same (groove or etch\$2 or recess\$3 or raise\$2) same pattern\$4) and (transfer\$3 or roll\$3 or collector) and (print\$3 near5 roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB